

Tzong-Lin Wu

List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/4100621/publications.pdf>

Version: 2024-02-01

253

papers

4,219

citations

159585

30

h-index

144013

57

g-index

254

all docs

254

docs citations

254

times ranked

1777

citing authors

#	ARTICLE	IF	CITATIONS
1	A Novel Compact Single-Stage Absorption Common-Mode Filter. IEEE Transactions on Electromagnetic Compatibility, 2022, 64, 111-118.	2.2	11
2	Wideband Reconfigurable Power Divider/Combiner in 40-nm CMOS for 5G mmW Beamforming System. IEEE Transactions on Microwave Theory and Techniques, 2022, 70, 1410-1422.	4.6	5
3	A Novel Absorptive Power Delivery Network for Power Noise Mitigation. IEEE Transactions on Electromagnetic Compatibility, 2022, 64, 536-542.	2.2	2
4	A Compact Symmetrical Single-Cell Bidirectional Absorption Common-Mode Filter. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2022, 12, 655-664.	2.5	4
5	A 0.6-dB Low Loss and 36°165 GHz Wideband Phase Difference Sub-THz Coupler in 0.18- μ m CMOS. IEEE Microwave and Wireless Components Letters, 2022, 32, 531-534.	3.2	0
6	A planar High-efficient W-band Substrate-Integrated-Waveguide Cavity-backed Slot Antenna Array. , 2022, , .		0
7	Poles and Stability of Full-Wave PEEC. IEEE Transactions on Antennas and Propagation, 2021, 69, 950-961.	5.1	3
8	Significant Crosstalk Reduction in High-Density Hollow Dielectric Waveguides by Photonic Crystal Fence. IEEE Transactions on Microwave Theory and Techniques, 2021, 69, 1316-1326.	4.6	4
9	Extraction of Complex Permittivity of Dielectrics on Package from W-band to D-band. , 2021, , .		4
10	Bridging the Gap Between Academia and Industry: MOST 6G Research Program in Taiwan. , 2021, , .		0
11	Extremely Low-Loss Planar Transition From Hollow Dielectric Waveguide to Printed Circuit Board for Millimeter-Wave Interconnect. IEEE Transactions on Microwave Theory and Techniques, 2021, 69, 4010-4020.	4.6	4
12	Corrections to "A Fully Integrated Arbitrary Power Divider on Printed Circuit Board by a Novel SMD-Resistor-Free Isolation Network". IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 1514-1514.	2.5	0
13	An Ultrawideband Common-Mode Filter with Cascaded Mushroom-like Structures. , 2021, , .		1
14	Eye Comparison Between Unencoded and 128b/130b-encoded NRZ Signals. , 2021, , .		0
15	A Novel Circuit Architecture of Bidirectional Common-Mode Noise Absorption Circuit. IEEE Transactions on Microwave Theory and Techniques, 2020, 68, 1476-1486.	4.6	12
16	Miniaturized Dual-Band FSS Suitable for Curved Surface Application. IEEE Antennas and Wireless Propagation Letters, 2020, 19, 2265-2269.	4.0	29
17	EMI Reduction Control Based on 8b/10b. , 2020, , .		0
18	A Cost-efficient Air-Filled Substrate Integrated Ridge Waveguide for mmWave Application. , 2020, , .		1

#	ARTICLE	IF	CITATIONS
19	A Fully Integrated Arbitrary Power Divider on Printed Circuit Board by a Novel SMD-Resistor-Free Isolation Network. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 1889-1901.	2.5	6
20	Balanced Bandpass Filter With Common-Mode Reflectionless Feature by Terminated Coupled Lines. IEEE Transactions on Electromagnetic Compatibility, 2020, 62, 1090-1097.	2.2	9
21	An Improved Method of Finding Complex Permittivity of Lossy Liquids. , 2020, , .		0
22	Novel Absorptive Balanced Bandpass Filters Using Resistive Loaded Transmission Lines. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 745-753.	2.5	14
23	A Synthesized Method for Common-Mode Noise Suppression Filters With Specified Common-Mode and Differential Mode Response. IEEE Transactions on Electromagnetic Compatibility, 2019, 61, 893-902.	2.2	21
24	A Resistor-Free N -Way Power Divider With Simultaneous Output Matching and Isolation. IEEE Microwave and Wireless Components Letters, 2019, 29, 523-525.	3.2	11
25	A High-Performance Common-Mode Noise Absorption Circuit Based on Phase Modification Technique. IEEE Transactions on Microwave Theory and Techniques, 2019, 67, 4394-4403.	4.6	13
26	Analysis and Design Method of a Novel Absorptive Common-Mode Filter. IEEE Transactions on Microwave Theory and Techniques, 2019, 67, 1826-1835.	4.6	23
27	Direct Simulation of the Full-Wave Partial Element Equivalent Circuit Using Standard SPICE [Application Notes]. IEEE Microwave Magazine, 2019, 20, 22-34.	0.8	7
28	Synthesized Method of Dual-Band Common-Mode Noise Absorption Circuits. IEEE Transactions on Microwave Theory and Techniques, 2019, 67, 1392-1401.	4.6	20
29	A mm-Wave Low-Loss Transition from Microstrip Line to Air-Filled Substrate Integrated Waveguide on Printed Circuit Board Technology. , 2019, , .		4
30	Enhanced Power and Signal Integrity Through Layout Optimization of High-Speed Memory Systems. , 2019, , .		2
31	Improvement of Power and Signal Integrity through Layer Assignment in High-Speed Memory Systems. , 2019, , .		1
32	Miniaturized Quarter-Wavelength Resonator for Common-Mode Filter Based on Pattern Ground Structure. , 2019, , .		1
33	Balanced-to-Balanced and Balanced-to-Unbalanced Power Dividers With Ultra-Wideband Common-Mode Rejection and Absorption Based on Mode-Conversion Approach. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 306-316.	2.5	17
34	Design and Modeling of a Compact Partially Transmissible Resistor-Free Absorptive Frequency Selective Surface for Wi-Fi Applications. IEEE Transactions on Antennas and Propagation, 2019, 67, 1306-1311.	5.1	9
35	Design of a Broadband Common-Mode Filter With Four Transmission Zeros. IEEE Transactions on Electromagnetic Compatibility, 2019, 61, 1052-1060.	2.2	10
36	EMI-Reduction Coding Based on 8b/10b. IEEE Transactions on Electromagnetic Compatibility, 2019, 61, 1007-1014.	2.2	1

#	ARTICLE	IF	CITATIONS
37	Design and Analysis of an Ultraminiaturized Frequency Selective Surface With Two Arbitrary Stopbands. IEEE Transactions on Electromagnetic Compatibility, 2019, 61, 1447-1456.	2.2	32
38	Codesign of Electrostatic Discharge Protection Device and Common Mode Suppression Circuit on Printed Circuit Board. IEEE Transactions on Electromagnetic Compatibility, 2018, 60, 1095-1101.	2.2	5
39	Dual-band WLAN MIMO antenna with a decoupling element for full-metallic bottom cover tablet computer applications. Microwave and Optical Technology Letters, 2018, 60, 1245-1251.	1.4	9
40	Broadband Eight-Port Forward-Wave Directional Couplers and Four-Way Differential Phase Shifter. IEEE Transactions on Microwave Theory and Techniques, 2018, 66, 2161-2169.	4.6	10
41	Ultracompact Via-Based Absorptive Frequency-Selective Surface for 5-GHz Wi-Fi With Passbands and High-Performance Stability. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 41-49.	2.5	16
42	Message from the Incoming Editor-in-Chief. IEEE Transactions on Electromagnetic Compatibility, 2018, 60, 1617-1618.	2.2	0
43	Signal/Power Integrity Co-Simulation of DDR3 Memory Module. , 2018, , .		7
44	Investigation on Degradation of Common Mode Noise Suppression with Electrostatic Discharge Protection Array. , 2018, , .		0
45	An Electromagnetic Bandgap Structure Integrated With RF LNA Using Integrated Fan-Out Wafer-Level Package for Gigahertz Noise Suppression. IEEE Transactions on Microwave Theory and Techniques, 2018, 66, 5482-5490.	4.6	15
46	A Common-Mode Filter with Three Alterable and Designable Transmission Zeroes. , 2018, , .		0
47	Modularized prototype of 5G mmWave base station system at 38 GHz. , 2018, , .		2
48	An eye diagram improvement method using simulation annealing algorithm. , 2018, , .		3
49	A Resistor-Free Absorptive Common-Mode Filter Using Gap-Coupled Resonator. IEEE Microwave and Wireless Components Letters, 2018, 28, 885-887.	3.2	15
50	A Novel Absorptive Common-Mode Filter for Cable Radiation Reduction. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 511-518.	2.5	29
51	An Accurate and Fast Substrate Noise Prediction Method With Octagonal TSV Model for 3-D ICs. IEEE Transactions on Electromagnetic Compatibility, 2017, 59, 1549-1557.	2.2	5
52	Analysis of Peak and Statistical Spectrum of Random Nonreturn-to-Zero Digital Signals. IEEE Transactions on Electromagnetic Compatibility, 2017, 59, 2002-2013.	2.2	0
53	The competitions of electromagnetic for undergraduate students in Taiwan: Taiwan creative electromagnetic implementation competition T-CEIC. , 2017, , .		0
54	A Novel and Compact Eight-Port Forward-Wave Directional Coupler With Arbitrary Coupling Level Design Using Four-Mode Control Technology. IEEE Transactions on Microwave Theory and Techniques, 2017, 65, 467-475.	4.6	22

#	ARTICLE	IF	CITATIONS
55	EMI-reduction coding based on 8b/10b. , 2017, , .		4
56	EBG-Based Grid-Type PDN on Interposer for SSN Mitigation in Mixed-Signal System-in-Package. IEEE Microwave and Wireless Components Letters, 2017, 27, 1053-1055.	3.2	8
57	A modal-analysis-based prediction method for radiation power in differential channels with discontinuity. , 2017, , .		1
58	A super broadband DGS-based common-mode filter with a compact dimension. , 2017, , .		0
59	A simple method to improve signal integrity of electrostatic discharge protection devices. , 2017, , .		1
60	Novel absorptive design of common-mode filter at desired frequency band. , 2016, , .		6
61	Balanced bandpass filter with reflectionless common-mode suppression. , 2016, , .		5
62	A radiation prediction method based on partial element equivalent circuit. , 2016, , .		0
63	Balanced bandpass filter with intrinsic common mode suppression using slot coupled lines and microstrip loading lines. , 2016, , .		3
64	E-shape resonator dualband common mode filter. , 2016, , .		3
65	Design and modeling of an absorptive frequency selective surface with several transmissive bands. , 2016, , .		2
66	A balanced-to-balanced power divider with common-mode noise absorption. , 2016, , .		3
67	Compact Cascaded-Spiral-Patch EBG Structure for Broadband SSN Mitigation in WLAN Applications. IEEE Transactions on Microwave Theory and Techniques, 2016, 64, 2740-2748.	4.6	19
68	A Resonator-Based Suppressor for Mitigating the Noise Transfer on Metal Plates for Control of Electromagnetic Interference. IEEE Microwave and Wireless Components Letters, 2016, 26, 906-908.	3.2	2
69	A Rigorous Proof on the Radiation Resistance in Generalized PEEC Model. IEEE Transactions on Microwave Theory and Techniques, 2016, 64, 4091-4097.	4.6	14
70	Beamforming broadside antenna array for 60-GHz technology. , 2016, , .		4
71	An Ultracompact TSV-Based Common-Mode Filter (TSV-CMF) in Three-Dimensional Integrated Circuits (3-D ICs). IEEE Transactions on Electromagnetic Compatibility, 2016, 58, 1128-1135.	2.2	28
72	Promoting Effective Education in Electromagnetics: Taiwan's School of Accessible and Visualized Electromagnetics Formed [Education Corner]. IEEE Antennas and Propagation Magazine, 2016, 58, 99-129.	1.4	6

#	ARTICLE	IF	CITATIONS
73	A Quadruplet-Resonator-Based Ferrite-Free Choke for Suppressing Noise Currents on Cable Shielding. IEEE Transactions on Microwave Theory and Techniques, 2016, 64, 86-95.	4.6	1
74	Investigation of the Radiated Emissions From High-Speed/High-Density Connectors. IEEE Transactions on Electromagnetic Compatibility, 2016, 58, 220-230.	2.2	6
75	SAVE and iEMPT: The EM revitalization program in Taiwan. , 2015, , .		0
76	Effective current distribution analysis method for multiconductor-transmission-line (MTL) system with arbitrary conductor number variation. , 2015, , .		0
77	Post-fabricated EBG tape on electronic devices for RFI mitigation in WLAN bands. , 2015, , .		0
78	A New Broadband Common-Mode Noise Absorption Circuit for High-Speed Differential Digital Systems. IEEE Transactions on Microwave Theory and Techniques, 2015, 63, 1894-1901.	4.6	56
79	Transmission-line based modeling for conformal shielding in advance system-in-package (SiP). , 2015, , .		3
80	Prediction of near-field shielding effectiveness for conformal-shielded SiP and measurement with magnetic probe. , 2015, , .		11
81	Compact hybrid open stub EBG structure for power noise suppression in WLAN band. , 2015, , .		4
82	A SMD-type filter solution for EMI/RFI mitigation on high-speed digital interfaces and its application. , 2015, , .		0
83	Compact wideband balanced filter for eliminating radio-frequency interference on differentially-fed antennas. , 2015, , .		4
84	Tri-section quarter wavelength resonator common mode filter. , 2015, , .		5
85	A prediction method of heat generation in the silicon substrate for 3-D ICs. , 2015, , .		0
86	Estimation Method for Statistical Eye Diagram in a Nonlinear Digital Channel. IEEE Transactions on Electromagnetic Compatibility, 2015, 57, 1655-1664.	2.2	19
87	A via-based methodology for frequency selective surface minimization. , 2015, , .		1
88	An Ultra-Compact Common-Mode Bandstop Filter With Modified-T Circuits in Integrated Passive Device (IPD) Process. IEEE Transactions on Microwave Theory and Techniques, 2015, 63, 3624-3631.	4.6	46
89	Suppression of end-fired emission for a miniaturized-element frequency-selective shielding surface with finite size using EBG. , 2015, , .		0
90	A Circular-Ring Miniaturized-Element Metasurface With Many Good Features for Frequency Selective Shielding Applications. IEEE Transactions on Electromagnetic Compatibility, 2015, 57, 365-374.	2.2	58

#	ARTICLE	IF	CITATIONS
91	An Effective Via-Based Frequency Adjustment and Minimization Methodology for Single-Layered Frequency-Selective Surfaces. IEEE Transactions on Antennas and Propagation, 2015, 63, 1641-1649.	5.1	48
92	Modeling and Analysis of Bandwidth-Enhanced Multilayer 1-D EBG With Bandgap Aggregation for Power Noise Suppression. IEEE Transactions on Electromagnetic Compatibility, 2015, 57, 858-867.	2.2	7
93	Investigation of signal integrity issues in multi-path electrostatic discharge protection device. , 2015, , .		7
94	A compact dual-band common-mode filtering component for EMC in wireless communication. , 2015, , .		3
95	Design of on-chip microwave filters in integrated fan-out wafer level packaging (InFO-WLP) technology. , 2015, , .		1
96	Very Closely Located Dual-Band Frequency Selective Surfaces via Identical Resonant Elements. IEEE Antennas and Wireless Propagation Letters, 2015, 14, 414-417.	4.0	26
97	A Novel Compact Balun Using a Weakly Coupled Line With Grounded Resonator. IEEE Microwave and Wireless Components Letters, 2014, 24, 763-765.	3.2	6
98	A Compact Loop-Slot Mode Combination Antenna for Ultra-Thin Tablet Computer With Metallic Bottom Cover. IEEE Antennas and Wireless Propagation Letters, 2014, 13, 746-749.	4.0	18
99	A novel common-mode filter (CMF) design based on signal interference technique. , 2014, , .		2
100	Fast prediction of radiation from high-speed/high-density connectors. , 2014, , .		2
101	Statistical eye diagram prediction for a 8b10b-coded channel using pulse response. , 2014, , .		7
102	Miniaturized and bandwidth-enhanced multilayer 1-D EBG structure for power noise suppression. , 2014, , .		5
103	A Novel 2.5-Dimensional Ultraminiaturized-Element Frequency Selective Surface. IEEE Transactions on Antennas and Propagation, 2014, 62, 3657-3663.	5.1	73
104	An Equation-Based Circuit Model and Its Generation Tool for 3-D IC Power Delivery Networks With an Emphasis on Coupling Effect. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2014, 4, 1062-1070.	2.5	12
105	A Novel Dual-Function Circuit Combining High-Speed Differential Equalizer and Common-Mode Filter With an Additional Zero. IEEE Microwave and Wireless Components Letters, 2014, 24, 617-619.	3.2	13
106	Synthesis Model and Design of a Common-Mode Bandstop Filter (CM-BSF) With an All-Pass Characteristic for High-Speed Differential Signals. IEEE Transactions on Microwave Theory and Techniques, 2014, 62, 1647-1656.	4.6	59
107	ABF-Based TSV Arrays With Improved Signal Integrity on 3-D IC/Interposers: Equivalent Models and Experiments. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 1744-1753.	2.5	25
108	Test Generation of Path Delay Faults Induced by Defects in Power TSV. , 2013, , .		2

#	ARTICLE	IF	CITATIONS
109	Bandwidth Enhancement of 4-Port Butler Matrix Using Broadband Forward-Wave Directional Coupler and Phase Difference Compensation. IEEE Transactions on Microwave Theory and Techniques, 2013, 61, 4099-4109.	4.6	36
110	The effect of various skew compensation strategies on mode conversion and radiation from high-speed connectors. , 2013, , .		10
111	A novel common-mode filter for multiple differential pairs with low crosstalk and low mode conversion level. , 2013, , .		1
112	Power distribution network modeling for 3-D ICs with TSV arrays. , 2013, , .		0
113	A Magnetic-Field Resonant Probe With Enhanced Sensitivity for RF Interference Applications. IEEE Transactions on Electromagnetic Compatibility, 2013, 55, 991-998.	2.2	59
114	Model and Mechanism of Miniaturized and Stopband-Enhanced Interleaved EBG Structure for Power/Ground Noise Suppression. IEEE Transactions on Electromagnetic Compatibility, 2013, 55, 159-167.	2.2	24
115	A Broadband Forward-Wave Directional Coupler Using Periodic Y-Shaped Ground Via Structures With Arbitrary Coupling Levels. IEEE Transactions on Microwave Theory and Techniques, 2013, 61, 38-47.	4.6	15
116	Overview of Signal Integrity and EMC Design Technologies on PCB: Fundamentals and Latest Progress. IEEE Transactions on Electromagnetic Compatibility, 2013, 55, 624-638.	2.2	166
117	Analytical Design of Via Lattice for Ground Planes Noise Suppression and Application on Embedded Planar EBG Structures. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 21-30.	2.5	27
118	Novel Differential-Mode Equalizer With Broadband Common-Mode Filtering for Gb/s Differential-Signal Transmission. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 1578-1587.	2.5	16
119	Active magnetic field canceling system. , 2013, , .		2
120	Compact TSV-based wideband bandpass filters on 3-D IC. , 2013, , .		5
121	Radio-frequency interference mitigation strategies for high-speed connectors. , 2013, , .		6
122	A novel compact 3-dB forward-wave directional coupler with periodic capacitive enhancement. , 2012, , .		1
123	A new solution and its estimation method for slot-crossing signals to reduce ISI-increased crosstalk. , 2012, , .		0
124	Low slow-wave effect and crosstalk for low-cost ABF-coated TSVs in 3-D IC interposer. , 2012, , .		10
125	A Branched Reflector Technique to Reduce Crosstalk Between Slot-Crossing Signal Lines. IEEE Microwave and Wireless Components Letters, 2012, 22, 342-344.	3.2	5
126	A novel dual-functional structure integrating differential-mode equalizer with common-mode filter for Gbps signaling. , 2012, , .		1

#	ARTICLE	IF	CITATIONS
127	A Compact and Embedded Balanced Bandpass Filter With Wideband Common-Mode Suppression on Wireless SiP. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 1030-1038.	2.5	32
128	A novel miniaturized bandstop filter using defected ground on system in package (SiP). , 2012, , .		0
129	Signal integrity design for GHz high-speed differential wires with slip ring capsule. , 2012, , .		1
130	Design considerations for radio frequency 3DICs. , 2012, , .		0
131	Eye prediction of digital driver with power distribution network noise. , 2012, , .		7
132	A New Model for Through-Silicon Vias on 3-D IC Using Conformal Mapping Method. IEEE Microwave and Wireless Components Letters, 2012, 22, 303-305.	3.2	40
133	A novel TSV model considering nonlinear MOS effect for transient analysis. , 2012, , .		12
134	Novel crosstalk modeling for multiple through-silicon-vias (TSV) on 3-D IC: Experimental validation and application to Faraday cage design. , 2012, , .		19
135	Radiation Suppression for Cable-Attached Packages Utilizing a Compact Embedded Common-Mode Filter. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 1696-1703.	2.5	69
136	3D simulation of substrate noise coupling from Through Silicon Via (TSV) and noise isolation methods. , 2012, , .		8
137	Bandwidth Enhancement Based on Optimized Via Location for Multiple Vias EBG Power/Ground Planes. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 332-341.	2.5	37
138	Mold-based compartment shielding to mitigate the intra-system coupled noise on SiP modules. , 2011, , .		14
139	A novel common mode choke and its application for 5 Gbps USB 3.0. , 2011, , .		9
140	Evaluation of magnetic field from varied permutation power transmission line at high technology nano-Fab. , 2011, , .		3
141	A broadband and miniaturized balun on system-in-package (SiP) technology. , 2011, , .		0
142	Suppression of RF interference using balanced filter in communication system. , 2011, , .		3
143	A novel and cost-effective method to suppress GHz common-mode radiation for slot-crossing differential lines. , 2011, , .		1
144	Active field canceling system in next generation nano-Fab. , 2011, , .		2

#	ARTICLE	IF	CITATIONS
145	Suppression of Common-Mode Radiation and Mode Conversion for Slot-Crossing GHz Differential Signals Using Novel Grounded Resonators. IEEE Transactions on Electromagnetic Compatibility, 2011, 53, 429-436.	2.2	6
146	A Novel Compact Forward-Wave Directional Coupler Design Using Periodical Patterned Ground Structure. IEEE Transactions on Microwave Theory and Techniques, 2011, 59, 1249-1257.	4.6	19
147	A Miniaturized and Broadband Balun Using Artificial Coupled Line With Imaginary Even-Mode Impedance. IEEE Transactions on Microwave Theory and Techniques, 2011, 59, 2233-2240.	4.6	5
148	A physics-based model of on-chip decoupling capacitor for accurate power integrity analysis. , 2011, , .		3
149	Analysis and design of GHz power noise isolation using 45° rotated photonic crystal fence. , 2011, , .		3
150	Bandwidth-enhanced EBG structure for power noise suppression in 60 GHz RF SiP. , 2011, , .		1
151	Accuracy-improved through-silicon-via model using conformal mapping technique. , 2011, , .		5
152	Mitigation of Noise Coupling in Multilayer High-Speed PCB: State of the Art Modeling Methodology and EBG Technology. IEICE Transactions on Communications, 2010, E93-B, 1678-1689.	0.7	21
153	A Broadband Chip-Level Power-Bus Model Feasible for Power Integrity Chip-Package Codesign in High-Speed Memory Circuits. IEEE Transactions on Electromagnetic Compatibility, 2010, 52, 235-239.	2.2	5
154	Overview of Power Integrity Solutions on Package and PCB: Decoupling and EBG Isolation. IEEE Transactions on Electromagnetic Compatibility, 2010, 52, 346-356.	2.2	181
155	Signal/Power Integrity Modeling of High-Speed Memory Modules Using Chip-Package-Board Coanalysis. IEEE Transactions on Electromagnetic Compatibility, 2010, 52, 381-391.	2.2	28
156	A Broadband and Miniaturized Common-Mode Filter for Gigahertz Differential Signals Based on Negative-Permittivity Metamaterials. IEEE Transactions on Microwave Theory and Techniques, 2010, 58, 195-202.	4.6	143
157	A Novel Miniaturized Forward-Wave Directional Coupler With Periodical Mushroom-Shaped Ground Plane. IEEE Transactions on Microwave Theory and Techniques, 2010, 58, 2277-2283.	4.6	17
158	An ultra compact common-mode filter for RF Interference control in 3G wireless communication systems. , 2010, , .		3
159	A novel time domain method to extract equivalent circuit model of patterned ground structures. , 2010, , .		0
160	Parallel-plate noise suppression using a ground surface perturbation lattice (GSPL) structure. , 2010, , .		5
161	A new bandstop filter using artificial defected ground structures with compact size and low radiation. , 2010, , .		3
162	A Novel Time Domain Method to Extract Equivalent Circuit Model of Patterned Ground Structures. IEEE Microwave and Wireless Components Letters, 2010, 20, 486-488.	3.2	14

#	ARTICLE	IF	CITATIONS
163	Design and Implementation of a Novel Hybrid Photonic Crystal Power/Ground Layer for Broadband Power Noise Suppression. IEEE Transactions on Advanced Packaging, 2010, 33, 206-211.	1.6	17
164	Design and Modelling of Miniaturized Bandgap Structure for Wideband GHz-Noise Suppression Based on LTCC Technology. IEEE Transactions on Advanced Packaging, 2010, 33, 630-638.	1.6	1
165	A Power Bus With Multiple Via Ground Surface Perturbation Lattices for Broadband Noise Isolation: Modeling and Application in RF-SiP. IEEE Transactions on Advanced Packaging, 2010, 33, 582-591.	1.6	15
166	A Novel Ground Resonator Technique to Reduce Common-Mode Radiation on Slot-Crossing Differential Signals. IEEE Microwave and Wireless Components Letters, 2010, 20, 660-662.	3.2	12
167	A novel and low-cost method for slot-crossing differential line to reduce GHz common-mode radiation in advanced PCB. , 2010, , .		0
168	A new common-mode EMI suppression technique for GHz differential signals crossing slotted reference planes. , 2010, , .		2
169	A stopband enhanced EBG power/ground plane based on via location design. , 2010, , .		2
170	Conformal shielding investigation for SiP modules. , 2010, , .		12
171	Design and Modeling of a Stopband-Enhanced EBG Structure Using Ground Surface Perturbation Lattice for Power/Ground Noise Suppression. IEEE Transactions on Microwave Theory and Techniques, 2009, 57, 2047-2054.	4.6	44
172	A metamaterial-typed differential transmission line with broadband common-mode suppression. , 2009, , .		9
173	Impact of Photonic Crystal Power/Ground Layer density on power integrity performance of high-speed power buses. , 2009, , .		4
174	An ultra compact electromagnetic band gap filter for GHz power noise suppression using LTCC technology. , 2009, , .		0
175	A GHz common-mode filter using negative permittivity metamaterial on low temperature co-fire ceramic (LTCC) substrate. , 2009, , .		9
176	Signal/power integrity design strategy for low-cost package of high-speed memory I/O interfaces. , 2009, , .		8
177	A Novel Wideband Common-Mode Suppression Filter for Gigahertz Differential Signals Using Coupled Patterned Ground Structure. IEEE Transactions on Microwave Theory and Techniques, 2009, 57, 848-855.	4.6	261
178	Anxiety levels in women undergoing prenatal maternal serum screening for Down syndrome: the effect of a fast reporting system by mobile phone short-message service. Prenatal Diagnosis, 2008, 28, 417-421.	2.3	34
179	A Novel Power/Ground Layer Using Artificial Substrate EBG for Simultaneously Switching Noise Suppression. IEEE Transactions on Microwave Theory and Techniques, 2008, 56, 1164-1171.	4.6	54
180	Power integrity chip-package-PCB co-simulation for I/O interface of DDR3 high-speed memory. , 2008, , .		9

#	ARTICLE	IF	CITATIONS
181	The effects on SI and EMI for differential coupled microstrip lines over LPC-EBG power/ground planes. , 2008, , .		4
182	Fundamentals of signal integrity. , 2008, , .		1
183	A novel stopband-enhanced EBG planes using an Embedded Slow-wave Structure in Low-cost RF-SiP. , 2008, , .		3
184	An Embedded Common-Mode Suppression Filter for GHz Differential Signals Using Periodic Defected Ground Plane. IEEE Microwave and Wireless Components Letters, 2008, 18, 248-250.	3.2	258
185	A novel HU-shaped common-mode filter for GHz differential signals. , 2008, , .		2
186	A novel broadband common-mode filter for high-speed differential signals. , 2008, , .		3
187	Parallel-plate noise isolation using a macro-via photonic crystal structure in advanced package. , 2008, , .		0
188	Chip-package-board co-design - a DDR3 system design example from circuit designers’ perspective. , 2008, , .		7
189	A low cost dual-CPW differential line for two layer PCBs. , 2008, , .		0
190	Modeling Noise Coupling Between Package and PCB Power/Ground Planes With an Efficient 2-D FDTD/Lumped Element Method. IEEE Transactions on Advanced Packaging, 2007, 30, 864-871.	1.6	29
191	A Novel EBG Power Plane with Stopband Enhancement using Artificial Substrate. , 2007, , .		7
192	Broadband Noise Suppression Using a Hybrid Photonic Crystal Power/Ground Plane Substrate. , 2007, , .		0
193	Theoretical demonstration of enhancement of light extraction of flip-chip GaN light-emitting diodes with photonic crystals. Applied Physics Letters, 2006, 89, 091116.	3.3	46
194	Improving the Radiated Immunity of the Strip-Lines Using a Novel Hybrid EBG Structure. , 2006, , .		1
195	A high electromagnetic immunity plastic composite package for a 10-gb/s optical transceiver module. Journal of Lightwave Technology, 2006, 24, 3195-3201.	4.6	1
196	Analysis of propagation characteristics for an octagonal photonic crystal fiber (O-PCF). Optics Communications, 2006, 258, 170-176.	2.1	84
197	New Package Scheme of a 2.5-Gb/s Plastic Transceiver Module Employing Multiwall Nanotubes for Low Electromagnetic Interference. IEEE Journal of Selected Topics in Quantum Electronics, 2006, 12, 1025-1032.	2.9	17
198	A photonic crystal power/ground layer for eliminating simultaneously switching noise in high-speed circuit. IEEE Transactions on Microwave Theory and Techniques, 2006, 54, 3398-3406.	4.6	39

#	ARTICLE	IF	CITATIONS
199	Embedded power plane with ultra-wide stop-band for simultaneously switching noise on high-speed circuits. Electronics Letters, 2006, 42, 213.	1.0	15
200	An electromagnetic crystal power substrate with efficient suppression of power/ground plane noise on high-speed circuits. IEEE Microwave and Wireless Components Letters, 2006, 16, 413-415.	3.2	8
201	A Time-Domain Approach for Extracting Broadband Macro- π Models of Differential Via Holes. IEEE Transactions on Advanced Packaging, 2006, 29, 789-797.	1.6	9
202	Characterizing package/PCB PDN interactions from a full-wave finite-difference formulation. , 2006, , .		4
203	Electromagnetic bandgap power/ground planes for wideband suppression of ground bounce noise and radiated emission in high-speed circuits. IEEE Transactions on Microwave Theory and Techniques, 2005, 53, 2935-2942.	4.6	212
204	A novel time-domain method for synthesizing broadband macro- π models of differential via. IEEE Microwave and Wireless Components Letters, 2005, 15, 378-380.	3.2	5
205	High electromagnetic shielding of plastic package for 2.5-Gb/s optical transceiver modules. IEEE Transactions on Advanced Packaging, 2005, 28, 89-95.	1.6	6
206	A novel power plane with super-wideband elimination of ground bounce noise on high speed circuits. IEEE Microwave and Wireless Components Letters, 2005, 15, 174-176.	3.2	147
207	An efficient approach for calculating the dispersions of photonic-crystal fibers: design of the nearly zero ultra-flattened dispersion. Journal of Lightwave Technology, 2005, 23, 2055-2061.	4.6	9
208	A novel ultraflattened dispersion photonic Crystal fiber. IEEE Photonics Technology Letters, 2005, 17, 67-69.	2.5	115
209	A Novel Time-Domain Algorithm for Synthesizing Broadband Macromodels of Coupled Interconnects. IEEE Transactions on Advanced Packaging, 2004, 27, 224-232.	1.6	3
210	Numerical and Experimental Investigation of Radiation Caused by the Switching Noise on the Partitioned DC Reference Planes of High Speed Digital PCB. IEEE Transactions on Electromagnetic Compatibility, 2004, 46, 33-45.	2.2	93
211	A novel approach for the incorporation of arbitrary linear lumped network into FDTD method. IEEE Microwave and Wireless Components Letters, 2004, 14, 74-76.	3.2	26
212	Rigorous Analysis of Polarization-Dependence Loss (PDL) for Equilateral π Fused Fiber Couplers. IEEE Photonics Technology Letters, 2004, 16, 165-167.	2.5	3
213	Photonic Crystal Fiber Analysis Through the Vector Boundary-Element Method: Effect of Elliptical Air Hole. IEEE Photonics Technology Letters, 2004, 16, 126-128.	2.5	28
214	A Novel Approach for Calculating the Dispersions of Photonic Crystal Fibers. IEEE Photonics Technology Letters, 2004, 16, 1492-1494.	2.5	10
215	A novel power planes with low radiation and broadband suppression of ground bounce noise using photonic bandgap structures. IEEE Microwave and Wireless Components Letters, 2004, 14, 337-339.	3.2	81
216	Low-Cost and Low-Electromagnetic-Interference Packaging of Optical Transceiver Modules. Journal of Lightwave Technology, 2004, 22, 2177-2183.	4.6	27

#	ARTICLE	IF	CITATIONS
217	A novel systematic approach for equivalent model extraction of embedded high-speed interconnects in time domain. IEEE Transactions on Electromagnetic Compatibility, 2003, 45, 493-501.	2.2	11
218	A vector power coupling model for analyzing polarization-dependent loss of equilateral triangular 3Å—3 weakly fused fiber couplers. Optics Communications, 2003, 224, 81-88.	2.1	5
219	Effective electromagnetic shielding of plastic packaging in low-cost optical transceiver modules. Journal of Lightwave Technology, 2003, 21, 1536-1543.	4.6	26
220	3-D Electromagnetic Modeling of Polarization-Dependent Coupling Characteristics of 1Å—3 Linear Array Weakly Fused Fiber Couplers. Fiber and Integrated Optics, 2003, 22, 415-432.	2.5	0
221	Real-time scheduling for elevator group systems. Systems Analysis Modelling Simulation, 2003, 43, 1675-1696.	0.1	1
222	More Analyses for the Service Performance of Elevator Group Systems. Systems Analysis Modelling Simulation, 2002, 42, 539-557.	0.1	0
223	An optimum approach for fabrication of low loss fused fiber couplers. Materials Chemistry and Physics, 2001, 69, 199-203.	4.0	19
224	The effect of test system impedance on measurements of ground bounce in printed circuit boards. IEEE Transactions on Electromagnetic Compatibility, 2001, 43, 600-607.	2.2	7
225	Electromagnetic shielding of plastic packaging in low-cost laser modules. Electronics Letters, 2000, 36, 118.	1.0	14
226	Three-dimensional electromagnetic modeling of fiber-core effects on the coupling characteristics of weakly fused tapered fiber-optic couplers. Journal of Lightwave Technology, 2000, 18, 1024-1030.	4.6	9
227	Vectorial analysis for polarization effect of wavelength-flattened fiber-optic couplers. Microwave and Optical Technology Letters, 1999, 23, 12-16.	1.4	3
228	Numerical modeling of weakly fused fiber-optic polarization beamsplitters. Part II: the three-dimensional electromagnetic model. Journal of Lightwave Technology, 1998, 16, 691-696.	4.6	32
229	Vectorial analysis of fiber-core effects in weakly fused couplers. IEEE Photonics Technology Letters, 1997, 9, 218-219.	2.5	4
230	Accurate coupling coefficients for fiber couplers with weakly fused cross sections. Applied Optics, 1995, 34, 6168.	2.1	5
231	A novel fabrication method for all-fiber, weakly fused, polarization beamsplitters. IEEE Photonics Technology Letters, 1995, 7, 786-788.	2.5	30
232	All-fiber Brewster windows made with extremely weakly fused asymmetric coupler. IEEE Photonics Technology Letters, 1995, 7, 1054-1056.	2.5	2
233	Rigorous analysis of form birefringence of weakly fused fiber-optic couplers. Journal of Lightwave Technology, 1995, 13, 687-691.	4.6	13
234	An efficient numerical approach, for determining the dispersion characteristics of dual-mode elliptical-core optical fibers. Journal of Lightwave Technology, 1995, 13, 1926-1934.	4.6	2

#	ARTICLE	IF	CITATIONS
235	Rigorous analysis of form birefringence of fused fibre couplers. Electronics Letters, 1994, 30, 998-999.	1.0	10
236	A novel periodic structures in photonic crystal fibers. , 0, , .		0
237	FDTD modeling of the coaxial feed effect on the measurement of the ground bounce in the high speed digital PCB. , 0, , .		0
238	EMI induced by the simultaneous switching noise on the partitioned DC planes. , 0, , .		0
239	The bridging effect of the isolation moat on the EMI caused by ground bounce noise between power/ground planes of PCB. , 0, , .		10
240	Crosstalk characterization of high-speed interconnects in time-domain. , 0, , .		1
241	Investigation of signal quality and radiated emission of microstrip line on imperfect ground plane: FDTD analysis and measurement. , 0, , .		11
242	Coupling of the ground bounce noise to the signal trace with via transition in partitioned power bus of PCB. , 0, , .		20
243	A time-domain approach to extract SPICE-compatible equivalent models for embedded interconnects. , 0, , .		0
244	NSTL evaluation of the compact EMC chamber with ferrite tiles being partially lined on the floor ground. , 0, , .		0
245	An efficient FDTD approach of modeling power-delivery-planes with SMT decoupling capacitors. , 0, , .		0
246	Photonic crystal fiber analysis through vector boundary-element method. , 0, , .		0
247	Electromagnetic shielding of plastic packaging in cost-effective optical transceiver modules. , 0, , .		2
248	Polarization and dispersion analysis of holey fibers with elliptical air holes through the vector boundary-element method. , 0, , .		0
249	Numerical and experimental investigation of noise coupling perturbed by ESD currents on printed circuit boards. , 0, , .		10
250	A low-cost plastic package for 2.5Gbps optical transceiver module with high electromagnetic shielding. , 0, , .		2
251	Analysis of radiation caused by SSN and transmission line by combining the equivalent circuits of active IC into FDTD. , 0, , .		7
252	A novel embedded power plane with 10Ghz stopband for simultaneous switching noise. , 0, , .		0

#	ARTICLE	IF	CITATIONS
253	A new frequency selective surface power plane with broad band rejection for simultaneous switching noise on high-speed printed circuit boards. , O, , .		6